



Product / Package Information	
Package	LGA_CAV
Body Size (mm)	5 X 2.8 X 1.2
Ball Count	12
Terminal Finish	Gold

Environmental Information	
RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Lid/Shield							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Composite	Polymer	147310-94-9	2.38 E-03	60.50	605000	9.23	92312
Composite	Glass oxide	65997-17-3	1.46 E-03	37.00	370000	5.65	56455
Composite	Carbon black	1333-86-4	9.84 E-05	2.50	25000	0.38	3815
Subtotal			3.94 E-03	100.0	1000000	15.26	152581

Laminate							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other organic materials	Bismaleimide Triazine, Epoxy resin	105-391-33-1/25722-66-1/9003-36-5	2.66 E-03	30.39	303943	10.30	103030
Other inorganic materials	Silica	60676-86-0	9.18 E-04	10.49	104936	3.56	35571
Other organic materials	Acrylic	Proprietary	8.74 E-04	10.00	99969	3.39	33987
Other organic materials	Epoxy Resin	7727-43-7	6.14 E-04	7.02	70165	2.38	23784
Copper & its alloys	Copper	7440-50-8	3.50 E-03	40.02	400186	13.57	135654
Nickel & its alloys	Nickel	7440-02-0	1.30 E-04	1.49	14902	0.51	5051
Precious Metals	Gold	7440-57-5	5.16 E-05	0.59	5899	0.20	2000
Subtotal			8.75 E-03	100.00	1000000	33.90	338977

Solder Land							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	4.30 E-04	74.68	746835	1.67	16653
Nickel & its alloys	Nickel	7440-02-0	1.24 E-04	21.52	215190	0.48	4798
Precious Metals	Gold	7440-57-5	2.18 E-05	3.80	37975	0.08	847
Subtotal			5.75 E-04	100.00	1000000	2.23	22388

Bond Wires							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.45 E-04	100	1000000	0.561	5612

Chip							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.96 E-03	100	1000000	7.60	75993

Die Attach 1							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Composite	Silanesilane, 1,1,1-trimethyl-N-(trimethylsilyl)-, hydrolysis products with silica	68909-20-6	6.87 E-05	37.00	370000	0.27	2664
Other organic materials	Bismaleimide monomer	Proprietary	5.11 E-05	27.50	275000	0.20	1980
Other inorganic materials	Silicon dioxide	7631-86-9	3.25 E-05	17.50	175000	0.13	1260
Other organic materials	Acrylate monomer	Proprietary	1.39 E-05	7.50	75000	0.05	540
Other organic materials	Epoxy resin	Proprietary	1.39 E-05	7.50	75000	0.05	540
Others	Additive	Proprietary	5.57 E-06	3.00	30000	0.02	216
Subtotal			1.86 E-04	100.00	1000000	0.72	7200

Die Attach 2							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.41 E-05	90.05	900524	0.09	933
Other organic materials	Methacrylate	9003-36-5	2.00 E-06	7.48	74794	0.01	78
Other organic materials	Bismaleimide resin	25068-38-6	6.60 E-07	2.47	24682	0.003	26
Subtotal			2.67 E-05	100.00	1000000	0.10	1036

Lid/ Shield Attach							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Thermoset	Epoxy resin	Proprietary	8.97 E-05	39.00	390000	0.35	3476
Other inorganic materials	Silicon dioxide	7631-86-9	8.05 E-05	35.00	350000	0.31	3120
Other organic materials	Amine	Proprietary	4.60 E-05	20.00	200000	0.18	1783
Other organic materials	Glycidyl ester	Proprietary	6.33 E-06	2.75	27500	0.02	245
Other organic materials	Cyanoguanidine	461-58-5	6.33 E-06	2.75	27500	0.02	245
Other inorganic materials	Carbon black	1333-86-4	1.15 E-06	0.5	5000	0.00	45
Subtotal			2.30 E-04	100.00	1000000	0.89	8974

Mold Compound							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Thermoset	Epoxy resin	258068-38-6	7.50 E-03	75.00	750000	29.05	290542
Other inorganic materials	Acid Anhydride	7631-86-9	2.40 E-03	24.00	240000	9.30	92973
Other organic materials	Amine	128-37-0	1.00 E-04	1.00	10000	0.39	3874
Subtotal			1.00 E-02	100.00	1000000	38.74	387389

Package Totals			Weight (g)	Percentage (%)	PPM
			2.58 E-02	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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